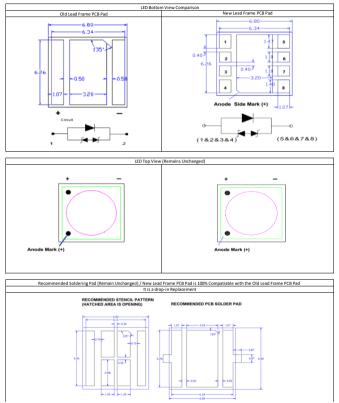
	PRODUCT CHANGE NOTIFICATIO	<u>DN</u>	
PCN No.:	10057	Date of Issue:	2017/08/2
Title of Change:	Lead Frame Pad Appearance Change     Z. Brightness (mW) Improvement	PCN Effective Date:	2017/08/2
Type of Change:	1. Mnor Cosmetic Change (Lead Frame PCB Pad Appearance Change)	Last Time Buy Date:	NA
Change Description:	<ol> <li>Increased Radkonetic Power I knightness (mN)</li> <li>Beginning immediately on and after August 28h, 2017. OT-Beightek will begin shipment of 04 PM886E LUCOX Elseries with a an updated land frame pcb pad. This is a drop-in replacement and will not after any form. It re- trochs. Newdering in the satisfiest policy of the source in supervised. The intervised policy of the current lead frame pad is depleted.</li> </ol>		
	2. Increased Radomatric Power (mW) due to increased chip performance and efficiency. Beginning immediately on and after August 259, 2017, 018 will sigh the affected parts with the new radiometric your etimoling structure to reflect the increased brightness. Outstomers may receive schements containing both the old and ever ardiametric binning (mW) structure for Dgilley until Dgikey inventory of the current binning structure is depleted.	Last Time Ship Date:	NA
Disposition of Old Product	Remaining inventory stock from Digkey can still be ordered until depleted.		
Reason for Change:	<ol> <li>The lead frame pcb supplier stopped producting original lead fame pad (old). A new lead frame pcb pad (drop-in replacement) will be used. New lead frame pad has a better design flexibility for manufacturer</li> </ol>		
	2. Optical pow er/brightness (mW) increased due to improved chip efficiency and performance		
Lot Number / Date Code Identification	CBH-Reselect-UX20XX series ships after August 25th, 2017 (date code:178825) owards will have the new leaf trans pead appearance and updated radiometric pow er / brightness (mW) binning structure. Customers will be able to leafly the new binning structure via the cade code (trom 170825 owa ards) and the bin code labels that are placed on the reel and packaging materials.		
Effect of Change on Product Fit, Form, or Function	Fit: Remains Unchanged, Form Remains Unchanged, Funchion: Unchanged. New lead frame pad is 100% compatible with the solder pad of the old lead frame pad. All other mechanical and leaderical parameters remain unchanged. No re-design for existing applications is required.		
	Reference To Change Types:	-	
	Accusition (Complete)     Acquisition (Partal)     Acquisition (Partal)     Folinciaton Site Compa (Jouiliteation / Country of     Childin (Ase Schenostration     Country of     Country of     Country of     Country of     Acquisition (Country of     Acquisition     Acquisitio		
	e Nom enclaturs Change Reversal e Process Change Design Change / Data Sheet Spec Change Packaging and Media		
	s Storage and Handling s Logistics Roadmap & Roadmap s Quality Alert Notifications w Autople Types		
	Environmental Announcement     New Component or Raw Material Added		

<u>/</u>	AFFECTED PARTS NUN	IBERS
MPN	Part Name	Replacement Part Number (if any
QBHP6868E-UV365K	6868 High Power UV LED 365nm	
QBHP6868E-UV385K	6868 High Power UV LED 385nm	
QBHP6868E-UV395K	6868 High Power UV LED 395nm	
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Datash	eet Version
QBHP68	58E-UVXXXK
Old	New
V1.1	V2.0



F @ IF=2000mA	
1. Max.	Unit
3.8	V
4.2	
	nA Unit
	Unit
	mW
00 1200	
1300	
00 1400	
	3         4.2           r Po for UV365K @ I <sub>F</sub> =2000r           n.         Max.           00         1100           00         1200           00         1300

		New (V2.0)	
Forward	Voltage V <sub>F</sub> @ I <sub>F</sub> =2	000mA	
Bin	Min.	Max.	Unit
A0	3.2	3.6	
A1	3.6	4.0	v
A2	4.0	4.4	
Bin	Min.	Max.	Unit
Radiomet	ric Power Po for	JV365K @ I⊧=200	0mA
P27	2700	2800	
P28	2800	2900	
P29	2900	3000	mW
P35	3000	3500	
Radiomet Bin	ric Power Po for	UV385K & UV395	K @ I <sub>F</sub> =2000mA
P35	3000	3500	
	0500	4000	
P40	3500		
P40 P45	4000	4500	mW